> Furthermore, with regard to claims 15 and 20-22, Applicants submit that the recited feature of "said resin projections extending downwards from the mount-surface and laterally extending from at least one of the resin package" is not disclosed in **Hiroshi**.

In the Office Action, the Examiner has urged that:

> Hiroshi in fact discloses the resin profusion portions, where the bond wires 15 go through and connect to the bottom conductors. Furthermore, the resin 14 in Hiroshi is an adhesive material and can be considered as a resin tape. This resin layer performs the same function as the tape that disclosed in claim 34. The metallic layer 2 is flush with the surface as mentioned above; see also fig. 4b-5 of Atsushi.

The Examiner is incorrect and has apparently either disregarded or overlooked our argument that **Hiroshi** fails to teach the feature of resin projection projecting from the bottom surface of the device. What is disclosed in **Hiroshi** is a resin part projecting from the bottom surface of the chip, but this resin part of **Hiroshi** does not project from the bottom surface of the device. The device of **Hiroshi** has a flat bottom surface.

Furthermore, as stated in Applicants' response:

> In regard to claim 10, **Hiroshi** discloses that connection member 14 comprising "insulative" resin. Applicants submit that this material is not the same as "resin tape."

Hosomi et al. has been cited for teaching the formation of metallic films 3 comprising a plurality of stacked metallic layers but, like **Hiroshi** discussed above, fails to teach, mention or suggest the electrode forming a flush surface with the package body, as recited in claim 34, from which claims 37-38 depend.

In particular, it should be noted that **Hiroshi** has an insulating substrate 11 underneath the chip. Because the resin fills the gap formed in the insulating substrate 11, there appears apparent similarity, **if the insulating substrate 11 is removed**. However, the insulating substrate 11 forms a part of the device of **Hiroshi** and cannot be removed. Thus, the device of **Hiroshi** is characterized by a flat bottom surface, contrary to the device of the present invention.

With regard to **Atsushi**, it is noted that the resin package body of **Atsushi** does have bottom projections, but the resin package body does not include the semiconductor chip therein. Thus, **Atsushi** fails to teach the feature of the resin package **sealing the chip**, contrary to the present invention.

Further, it is noted that the device of **Hiroshi** is designed to have a flat bottom surface in view of the intended use of the device in a plastic IC card 21 as represented in Fig. 4 of **Hiroshi**. Thus, there would be no motivation for a person skilled in the art to form the projections taught by **Atsushi** on the flat bottom surface of the device of **Hiroshi**.

In view of the foregoing remarks, the 35 USC §103(a) rejection should be reconsidered and withdrawn and a Notice of Allowance be mailed.

If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicants undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. Please charge any fees for such an extension of time and any other

fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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